

## ● **Bill of Materials**

- ✧ Component Part number and description (include rating value and tolerance where applicable).
- ✧ Reference designators with corresponding quantities
- ✧ Component manufacturers (preferred or stipulated).
- ✧ Indicate approved alternate components
- ✧ If firmware is required, please list each firmware as a BOM line item(include revision)

## ● **PCB Gerber files**

- ✧ Gerber data comprising every 'layer' required to manufacture and supply the PCB with descriptive exported 'read me' file. If no silkscreen, identification is required to the finished PCB, please issue a .pdf file (or similar) depicting the component locations, orientations, and relevant assembly notes.
- ✧ PCB manufacturing rule including Number of Layers, Board Thickness, Board Material, Copper Thickness, Color of Solder Mask and Finish.

## ● **Requirements**

- ✧ Solder type: Leaded or Lead-free?
- ✧ Compliance: RoHS or Non-RoHS?
- ✧ Special instructions/processes:
  - Pre-bake
  - Conformal coat
  - Potting
  - Others
- ✧ Required quote qty

## ● **Testing (if applicable)**

- ✧ Test/burn-in requirements (include procedures)
- ✧ Describe test equipment required
- ✧ Schematic(s) (PDF preferred)

## ● **Box Build (if applicable)**

- ✧ Mechanical assembly drawings and specifications (PDF, Solid Works, PRO/E are all acceptable)

## ● **Not Required, But Preferred**

- ✧ Assembly drawings for SMT component locations/orientation